Product End-of-Life Disassembly Instructions

Product Category: Data Storage Devices

Marketing Name / Model
[List multiple models if applicable.]

DAT160m (array module) / Q1575X. Where X = any alphanumeric combination

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	**Tool Size (if applicable)**
Crosshead screwdriver	
Torx screwdriver	T-10
Nippers	N/A

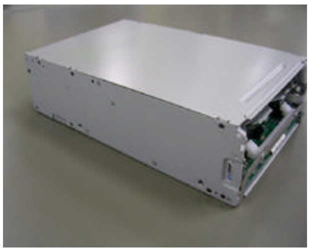
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

3.1.1. Remove the array cradle from the mechanism. Secured with 4 x T-10 screws – 2 x on either side. Remove the 1 x SCSI I/O PCA > 10 square cm's from the cradle using a T-10.
Remove metal wing brackets (5.25" product only, 4 x T-10 screws) and the front panel.
3.1.2. Remove side panels and the lid by unscrewing 14 x crosshead (CH) screws from each side. See image 1. Remove the lid by removing 1 x CH screw at the rear of the mechanism (See image 2) and 2 x CH screws at the front top of the mechanism. See image 3.
3.1.3. Remove the base and the cartridge assembly (see image 4) and remove 1 x CH screw from the BOM-ASSY. (see image 5)
3.1.4. Unlock and release FFCs and FPCs from the PCA (see image 6).
3.1.5. Unscrew 5 x CH screws from the base of the PCA and remove main PCA (> 10 sq cm). See images 7&8.
3.1.6. Remove REC-SW-PCA (> 10 square cm's). See image 9.
3.1.7. Remove ARM-HOUSING, HC-W-ASSY, ARM-P8-SUB-ASSY, the GUIDE-V-PR, and PR-ASSY from drive to access the MODE-DRIVE-ASSY. (see images 10 and 11)
1.1.8. Unlock FFC connector and release FFC-9pin. Unscrew 6 x CH screws and remove MODE-DRIVE-ASSY. See image 12.
1.1.9. Cut out the 4 x wires from the mode-drive-assembly and unscrew the 4 x CH screws to release the PWB-MODE-A. PWB-MODE-A is > 10 square cm's. See image 13.
1.1.11 Remove 5 x CH screws to release the P-SUB-CHASSIS, 7 x CH screws to remove the REEL-MOTOR and PWB-MODE-B-ASSY and 3 x CH screws to release the DRUM-ASSY. PWD-MODE-B-ASSY is > 10 square cm's. See image 14.

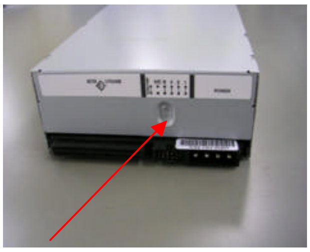
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1)



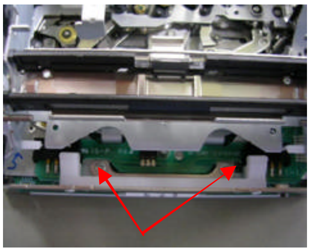
Remove 14 screws per side.

2)



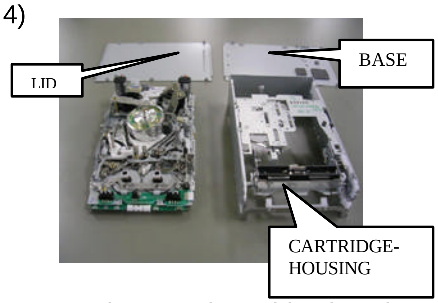
Remove M1.7 screw a rear side.

3)



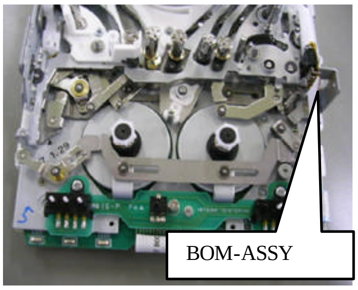
Remove 2 x M1.7 screws at front top.

4)



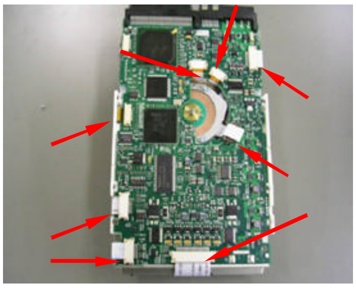
Remove base and cartridge housing

5)



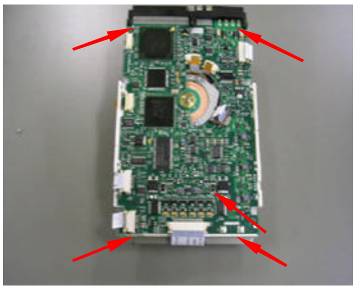
Remove 1 x CH screw from BOM ASSY

6)



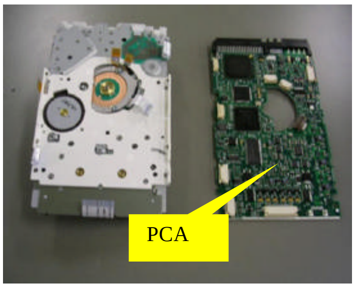
Unlock and release FFCs and FPCs from the PCA.

7)



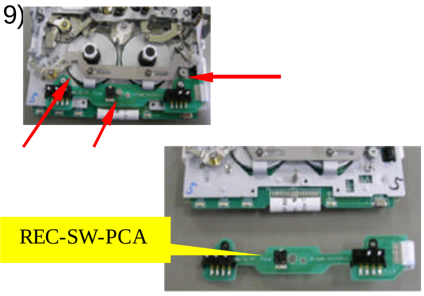
Remove 5 x CH screws to remove the PCA

8)



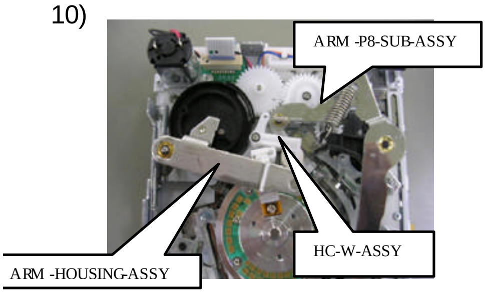
Remove main PCA (> 10 square cm's).

9)

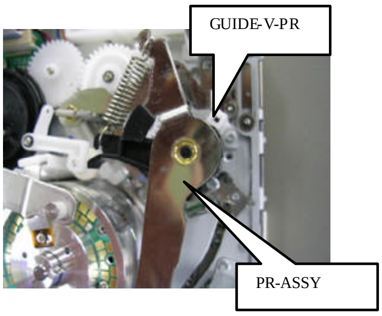


Unscrew 3 x CH screws to remove the REC-SW-PCA-assembly (> 10 square cm's)

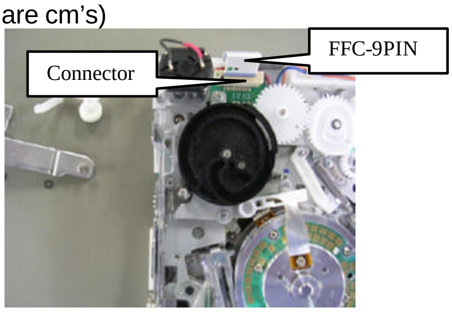
10)



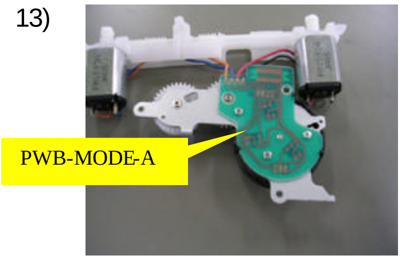
11)



12)

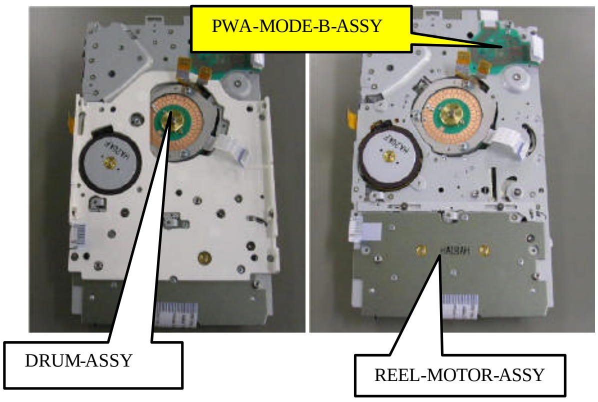


13)



Clip 4 wires and remove 3 screws.
PWB-MODE-A is > 10 square cm's

14)



Remove PWA-MODE-B-ASSY > 10 square cm's